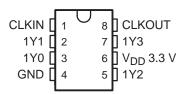
SCAS640D - JULY 2000 - REVISED JULY 2002

- Phase-Lock Loop Clock Driver for Synchronous DRAM and General-Purpose Applications
- Spread Spectrum Clock Compatible
- Operating Frequency: 24 MHz to 200 MHz
- Low Jitter (Cycle-cycle): <|150 ps| Over the Range 66 MHz–200 MHz
- Distributes One Clock Input to One Bank of Five Outputs (CLKOUT Is Used to Tune the Input-Output Delay)
- Three-States Outputs When There Is no Input Clock
- Operates From Single 3.3-V Supply
- Available in 8-Pin TSSOP and 8-Pin SOIC Packages
- Consumes Less Than 100 μA (Typically) in Power Down Mode
- Internal Feedback Loop Is Used to Synchronize the Outputs to the Input Clock
- 25-Ω On-Chip Series Damping Resistors
- Integrated RC PLL Loop Filter Eliminates the Need for External Components

D OR PW PACKAGE (TOP VIEW)



description

The CDCVF2505 is a high-performance, low-skew, low-jitter, phase-lock loop (PLL) clock driver. It uses a PLL to precisely align, in both frequency and phase, the output clocks (1Y[0–3] and CLKOUT) to the input clock signal (CLKIN). The CDCVF2505 operates at 3.3 V. It also provides integrated series-damping resistors that make it ideal for driving point-to-point loads.

One bank of five outputs provides low-skew, low-jitter copies of CLKIN. Output duty cycles are adjusted to 50 percent, independent of duty cycle at CLKIN. The device automatically goes in power-down mode when no input signal is applied to CLKIN.

Unlike many products containing PLLs, the CDCVF2505 does not require an external RC network. The loop filter for the PLLs is included on-chip, minimizing component count, space, and cost.

Because it is based on the PLL circuitry, the CDCVF2505 requires a stabilization time to achieve phase lock of the feedback signal to the reference signal. This stabilization is required following power up and application of a fixed-frequency, fixed-phase signal at CLKIN, and following any changes to the PLL reference.

The CDCVF2505 is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

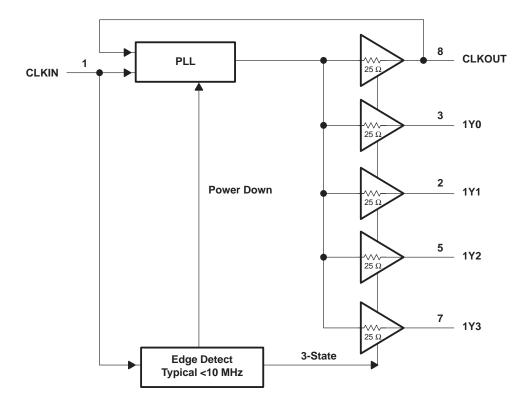


FUNCTION TABLE

INPUT	OUTPUTS		
CLKIN	1Y (0:3) CLKOU		
L	L	L	
Н	Н	Н	
<10 MHz†	Z	Z	

 $^{^\}dagger$ Typically, below 2 MHz the device goes in power-down mode in which the PLL is turned off and the outputs enter into Hi-Z mode. If a >10-MHz signal is applied at CLKIN the PLL turns on, reacquires lock, and stabilizes after approximately 100 μs . The outputs will then be enabled.

functional block diagram





Terminal Functions

TERM	INAL	1/0	DESCRIPTION
NAME	NO.	I/O	DESCRIPTION
1Y[0-3]	2, 3, 5, 7	0	Clock outputs. These outputs are low-skew copies of CLKIN. Each output has an integrated 25- Ω series damping resistor.
CLKIN	1	I	Clock input. CLKIN provides the clock signal to be distributed by the CDCVF2505 clock driver. CLKIN is used to provide the reference signal to the integrated PLL that generates the clock output signals. CLKIN must have a fixed frequency and fixed phase for the PLL to obtain phase lock. Once the circuit is powered up and a valid signal is applied, a stabilization time (100 μ s) is required for the PLL to phase lock the feedback signal to CLKIN.
CLKOUT	8	0	Feedback output. CLKOUT completes the internal feedback loop of the PLL. This connection is made inside the chip and an external feedback loop should NOT be connected. CLKOUT can be loaded with a capacitor to achieve zero delay between CLKIN and the Y outputs.
GND	4	Power	Ground
V _{DD3.3} V	6	Power	3.3-V Supply

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range, V _{DD}	
Input voltage range, V _I (see Notes 1 and 2)	
Output voltage range, VO (see Notes 1 and 2)	
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$)	±50 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{DD})	±50 mA
Continuous total output current, I_O ($V_O = 0$ to V_{DD})	±50 mA
Package thermal impedance, θ_{JA} (see Note 3): D package	165.5°C/W
PWR package	230.5°C/W
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This value is limited to 4.3 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V _{DD}	3	3.3	3.6	V
High-level input voltage, V _{IH}	0.7 V _{DD}			V
Low-level input voltage, V _{IL}			0.3 V _{DD}	V
Input voltage, V _I	0		V_{DD}	V
High-level output current, IOH			-12	mA
Low-level output current, I _{OL}			12	mA
Operating free-air temperature, T _A	-40		85	°C

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timing requirements over recommended ranges of supply voltage and operating free-air temperature

			MIN	NOM	MAX	UNIT
fclk	Clock frequency		24		200	MHz
lament alocale districtionals		24 MHz – 85 MHz (see Note 4)	30%		85%	
	Input clock duty cycle	86 MHz – 200 MHz	40%	50%	60%	
	Stabilization time (see Note 5)				100	μs

NOTES: 4. Ensured by design but not 100% production tested.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER		TEST CONDITIONS	V _{DD}	MIN	TYP [†]	MAX	UNIT	
VIK	Input voltage		I _I = -18 mA	3 V			-1.2	V	
		I _{OH} = -100 μA	MIN to MAX	V _{DD} -0.2					
Vон	VOH High-level output voltage		I _{OH} = -12 mA	3 V	2.1			V	
			I _{OH} = -6 mA	3 V	2.4				
			I _{OL} = 100 μA	MIN to MAX			0.2		
VOL	V _{OL} Low-level output voltage		I _{OL} = 12 mA	3 V			0.8	V	
			I _{OL} = 6 mA	3 V			0.55		
la	High-level output current		V _O = 1 V	3 V	-27			mA	
ЮН	nigh-level output current		V _O = 1.65 V	3.3 V		-36		mA	
lo.	Low lovel output ourrent		V _O = 2 V	3 V	27			mA	
IOL	Low-level output current		V _O = 1.65 V	3.3 V		40		IIIA	
II	Input current		$V_I = 0 V \text{ or } V_{DD}$				±5	μΑ	
Ci	Input capacitance		$V_I = 0 V \text{ or } V_{DD}$	3.3 V		4.2		pF	
C	Output conscitones	Yn	\\\ - 0 \\ or \\\	3.3 V		2.8		n.E	
Co	Output capacitance CLKOUT	CLKOUT	$V_I = 0 \text{ V or } V_{DD}$			5.2		pF	

[†] All typical values are at respective nominal V_{DD} and 25°C.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 25 pF, V_{DD} = 3.3 V \pm 0.3 V (see Note 5)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
tpd	Propagation delay (normalized (see Figure 3)	CLKIN to Yn, f= 66 MHz to 200 MHz	-150		150	ps
tsk(o)	Output skew (see Note 6)	Yn to Yn			150	ps
+	Jitter (cycle to cycle) (see Figure 5)	f = 66 MHz to 200 MHz		70	150	no
^t c(jit_cc)	Sitter (cycle to cycle) (see Figure 5)	f = 24 MHz to 50 MHz		200	400	ps
odc	Output duty cycle (see Figure 4)	f = 24 MHz to 200 MHz at 50% V _{DD}	45%		55%	
t _r	Rise time	V _O = 0.4 V to 2 V	0.5		2	ns
t _f	Fall time	V _O = 2 V to 0.4 V	0.5		2	ns

[†] All typical values are at respective nominal V_{DD} and 25°C.

NOTE 6: The $t_{sk(0)}$ specification is only valid for equal loading of all outputs.



^{5.} Time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal. For phase lock to be obtained, a fixed-frequency, fixed-phase reference signal must be present at CLKIN. Until phase lock is obtained, the specifications for propagation delay, skew, and jitter parameters given in the switching characteristics table are not applicable. This parameter does not apply for input modulation under SSC application.

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ESD information

ESD MODELS	LIMIT
Human Body Model (HBM)	2.0 kV
Machine Model (MM)	300 V
Charge Device Model (CDM)	1 kV

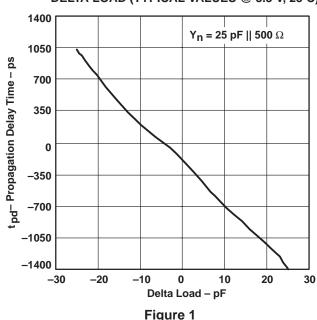
thermal information

	CDCVF2505 8-PIN SOIC			THERMAL AIR FLOW (CFM)			
	CDCVF2505 6-FIN SOIC		0	150	250	500	UNIT
$R_{\theta JA}$	High K		97	87	83	77	°C/W
$R_{\theta JA}$	Low K		165	126	113	97	°C/W
$R_{\theta JC}$	High K	39					°C/W
$R_{\theta JC}$	Low K	42					°C/W

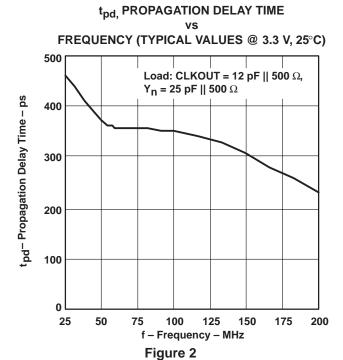
	CDCVE2505 9 DIN TSSOR			THERMAL AIR FLOW (CFM)				
CDCVF2505 8-PIN TSSOP			0	150	250	500	UNIT	
$R_{\theta JA}$	High K		149	142	138	132	°C/W	
$R_{\theta JA}$	Low K		230	185	170	150	°C/W	
$R_{\theta JC}$	High K	65					°C/W	
$R_{\theta JC}$	Low K	69					°C/W	

TYPICAL CHARACTERISTICS

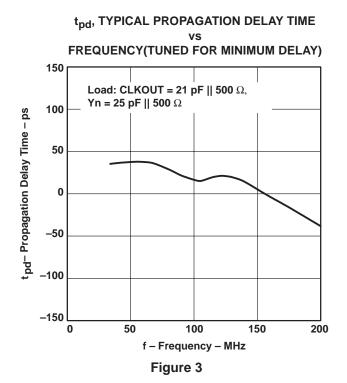
t_{pd}, PROPAGATION DELAY TIME vs
DELTA LOAD (TYPICAL VALUES @ 3.3 V, 25°C)

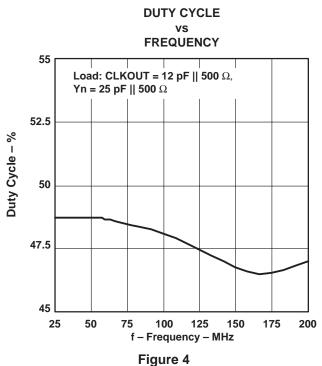


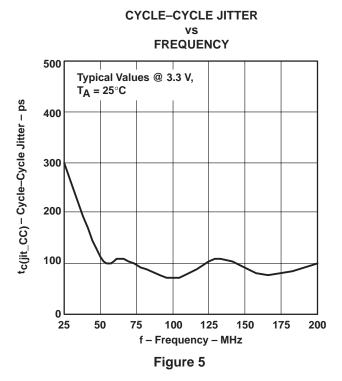
NOTE: Delta Load = CLKOUT Load - Yn Load

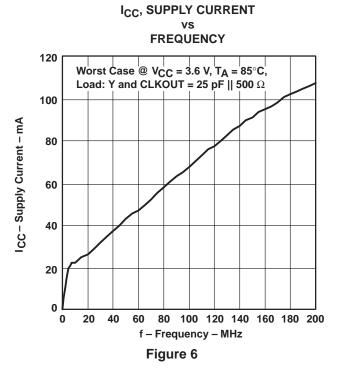


TYPICAL CHARACTERISTICS









PARAMETER MEASUREMENT INFORMATION

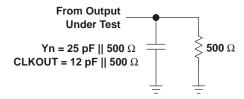


Figure 7. Test Load Circuit

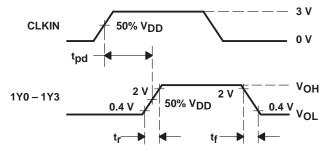
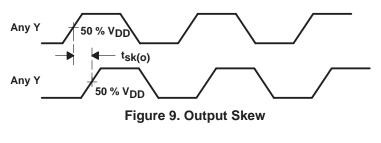


Figure 8. Voltage Threshold for Measurements, Propagation Delay (tpd)



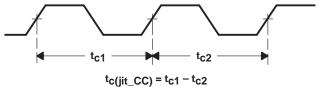
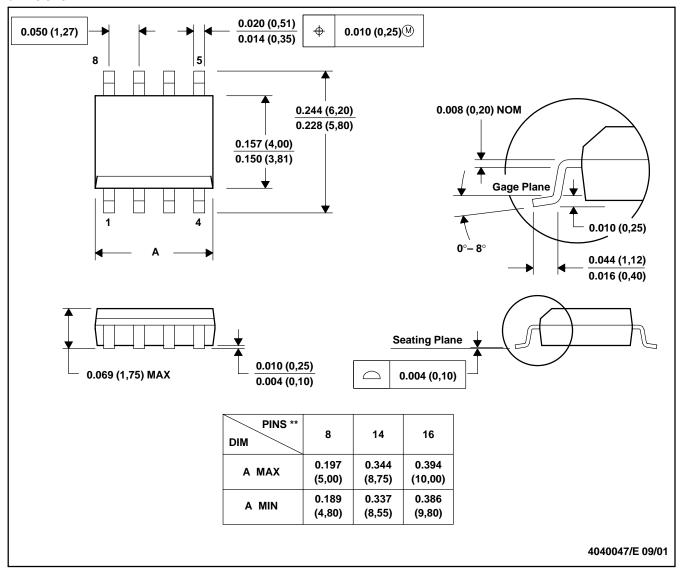


Figure 10. Cycle-to-Cycle Jitter

D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

8 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

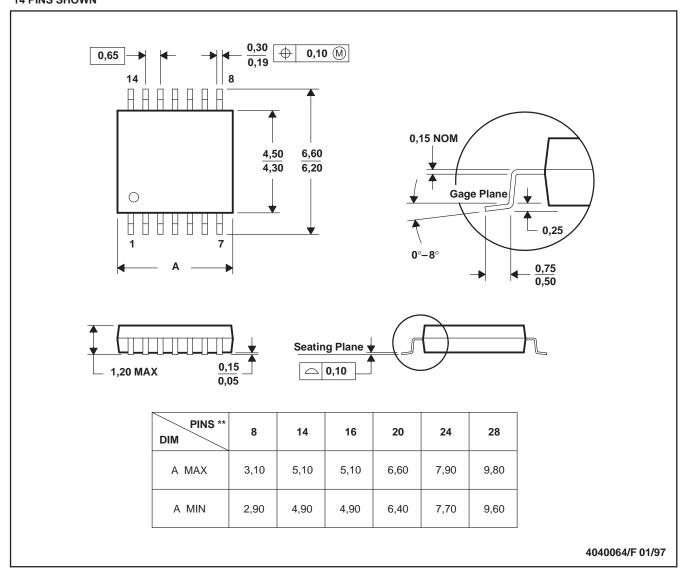
C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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